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Publications List of Dr. H. Vennila

International Publication:

- 1. **Vennila, H.**, and T. Ruban Deva Prakash. "Particle swarm optimization technique for solving economic emission dispatch problems." *Procedia engineering* 38 (2012): 2009-2021.
- 2. **Vennila, H.**, T. Ruban Deva Prakash, B. G. Malini, M. S. Birundha, V. Evangelin Jeba, and L. Sumi. "Application of genetic algorithm for solving optimum power flow problems." *International Journal of Information Systems and Supply Chain Management (IJISSCM)* 6, no. 2 (2013): 62-71.
- 3. **Vennila, H.**, T. Ruban Deva Prakash, and T. Ruban. "A Solution for Environmental Constrained Economic Dispatch Problems using Honey Bee Algorithm." *International Journal of Computer Applications* 975 (2012): 8887.
- 4. **Vennila, H.**, B. G. Malini, V. Evangelin Jeba, and T. Ruban Deva Prakash. "Economic emission dispatch of thermal generating units using genetic algorithm technique." *International Journal of Enterprise Network Management* 4, no. 4 (2011): 344-353.
- 5. **Vennila, H.**, T. Ruban Deva Prakash, B. G. Malini, M. S. Birundha, L. Sumi, and V. Jeba. "Application of simulated annealing and genetic algorithm for solving optimum power flow problems." *International Journal of Logistics Economics and Globalisation* 2, no. 4 (2010): 390-402.
- 6. **Vennila, H.**, T. Ruban Deva Prakash, B. G. Malini, M. S. Birundha, V. Evangelin Jeba, and L. Sumi. "Application of genetic algorithm for solving optimum power flow problems." *International Journal of Information Systems and Supply Chain Management (IJISSCM)* 6, no. 2 (2013): 62-71.

International Conference:

7. **Vennila, H**., and R. Rajesh. "A solution of combined static and dynamic Dispatch Problems using HB-SA Algorithm with valve point Effects." In *2018 International Conference on Smart Systems and Inventive Technology (ICSSIT)*, pp. 159-162. IEEE, 2018.